



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-03-06
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RVW8*UX64AA5	A	ZS1A	2017-03-06
Amount	UoM	Unit type	ST ECOPACK Grade	
6.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2x1.26x0.93	5	gull wing	
Comment	Package: W8 SOT 323 SLDS; MDF valid for LDK130C10R			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-12th January 2017

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RVW8*UX64AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.422	mg	supplier	die	Silicon (Si)	7440-21-3		0.402	mg	952607	67000
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	9479	667
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	7109	500
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	2370	167
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	16588	1167
				supplier	polymer die coating	PIX1 Polyimide	108-65-6		0.001	mg	2370	167
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.004	mg	9479	667
Leadframe	Copper & its alloys	1.362	mg	supplier	Alloy	Copper (Cu)	7440-50-8		1.312	mg	963289	218667
				supplier	Alloy	Iron (Fe)	7439-89-6		0.031	mg	22761	5167
				supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	1468	333
				supplier	metallization	Nickel (Ni)	7440-02-0		0.016	mg	11747	2667
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	734	167
Die attach	Other Organic Materials	0.051	mg	supplier	glue	Silver (Ag)	7440-22-4		0.040	mg	784314	6667
				supplier	glue	Carbocyclic Acrylates	proprietary		0.005	mg	98039	833
				supplier	glue	Bismaleimide resin	35325-39-4		0.001	mg	19608	167
				supplier	glue	2-preponoic acid, 2-methyl	68586-19-6		0.001	mg	19608	167
				supplier	glue	Additive	proprietary		0.001	mg	19608	167
				supplier	glue	Dicumyl peroxide	80-43-3		0.003	mg	58824	500
Bonding wires	Other inorganic materials	0.016	mg	supplier	wire	Copper (Cu)	7440-50-8		0.016	mg	1000000	2667
Encapsulation	Other Organic Materials	4.149	mg	supplier	mold compound	Epoxy Resin-1	Proprietary		0.124	mg	29887	20667
				supplier	mold compound	Epoxy Resin-2	25068-38-6		0.124	mg	29887	20667
				supplier	mold compound	Phenol resin	29690-82-2		0.186	mg	44830	31000
				supplier	mold compound	Silica	60676-86-0		3.624	mg	873463	604000
				supplier	mold compound	Carbon Black	1333-86-4		0.008	mg	1928	1333
supplier	mold compound	Others			0.083	mg	20005	13833				